



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Stephan Grunow, et al.

Serial No.: 10/688,452

Filed: October 18, 2003

Examiner: Not Assigned

Art Unit: N/A

Docket No: TI-35917 (1207-013)

For: A STACKED INTERCONNECT STRUCTURE BETWEEN COPPER  
LINES OF A SEMICONDUCTOR CIRCUIT

PRELIMINARY AMENDMENT

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(A)	
I hereby certify that the above correspondence is being deposited with	
the U.S. Postal Service as first Class Mail in an envelope addressed to	
Mail Stop Non-Fee Amendment, Commissioner for Patents, PO Box	
1450, Alexandria, VA 22313-1450.	
Date	<u>2-19-04</u>
	<u>Marianna Smith</u>
Marianna Smith	

Sir:

Please amend the above-referenced application as follows: